
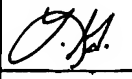

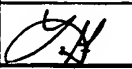




FORM PTO-1449	SERIAL NO. 10/777,608	CASE NO. 2003 P 54807 US (BHGL No. 10808/119)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE February 11, 2004	GROUP ART UNIT 2812
(use several sheets if necessary)		APPLICANT(S): Heinrich Ollendorf et al.

EXAMINER INITIAL	OTHER ART – NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
	A1	Kelly H. Block, Heather L. Rayle, "Integration of CMP with Low-k Materials", Semiconductor International, Entegris, Reed Business Information, a division of Reed Elsevier Inc., (June 1, 2002), 7 pages.
	A2	Maria A. Lester, Associate Editor, "Post-CMP Cleaning Enhanced on Ploy-Si Film", Semiconductor International, Focus Dry, Reed Business Information, a division of Reed Elsevier Inc., (July 1, 2002), 2 pages.
	A3	Souvik Banerjee, Andrea Via, Harlan F. Chung, Robert J. Small, "Combining Aqueous and Cryogenic Post-CMP Cleaning", Semiconductor International, Solid State Equipment Corporation, Reed Business Information, a division of Reed Elsevier Inc., (February 1, 2003), 7 pages.
	A4	Michael R. Oliver, "Chemical Mechanical Polishing", Semiconductor International, ASML, Reed Business Information, a division of Reed Elsevier Inc., (June 1, 2003), 2 pages.

EXAMINER 	DATE CONSIDERED 9/28/05
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.